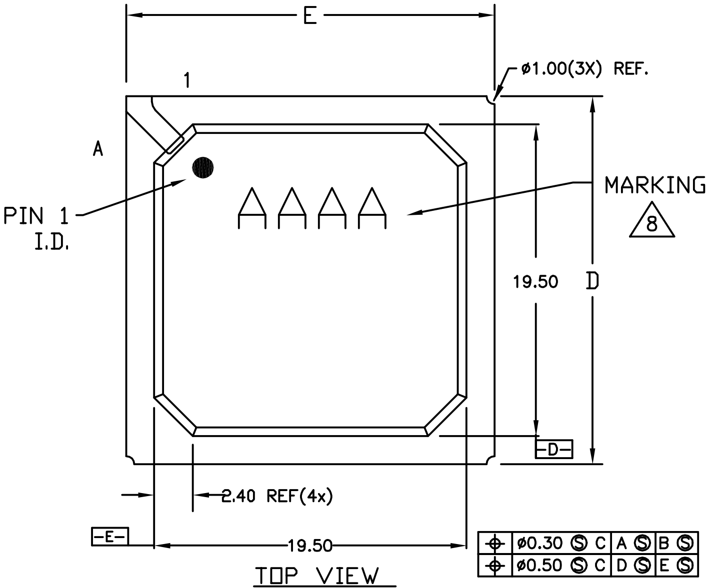
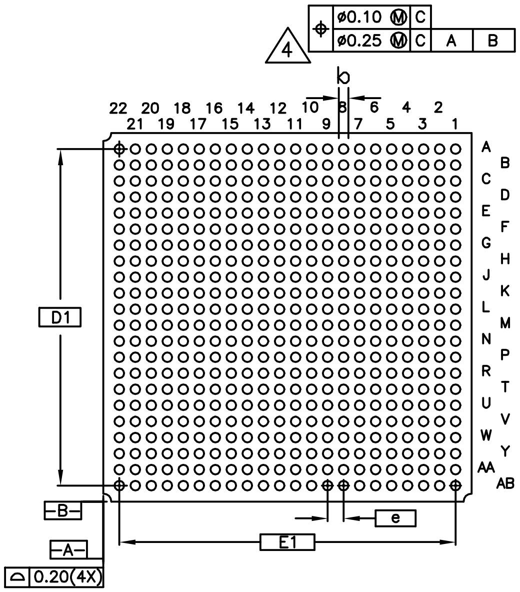
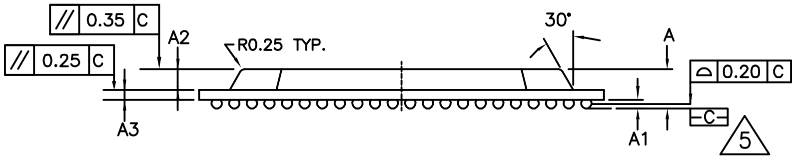


TOP VIEW



BOTTOM VIEW
(BALL SIDE)

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.90	2.03	2.16
A1	0.40	0.50	0.60
A2		0.97 REF	
A3		0.56 REF	
D	23.00		
D1	21.00 BSC		
E	23.00		
E1	21.00 BSC		
b		0.60	
e	1.0 BSC		
M	22		
N	484		
Pkg. Code: V484T-4			



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. 'e' REPRESENTS THE BASIC SOLDER BALL PITCH.
3. 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE. 'N' IS THE NUMBER OF ATTACHED SOLDER BALLS.
4. 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM -C- .
5. PRIMARY DATUM -C- AND THE SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THE OVERALL PACKAGE THICKNESS "A" ALREADY CONSIDERS COLLAPSE BALLS.
7. REFERENCE JEDEC MO-205.
8. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
9. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.

-DRAWING NOT TO SCALE-

MAXIM

TITLE:
PACKAGE OUTLINE,
484 BALL BGA, 23x23x2.03mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
SCOTT SCHROEDER 02/19/09	21-0447	A	1/1